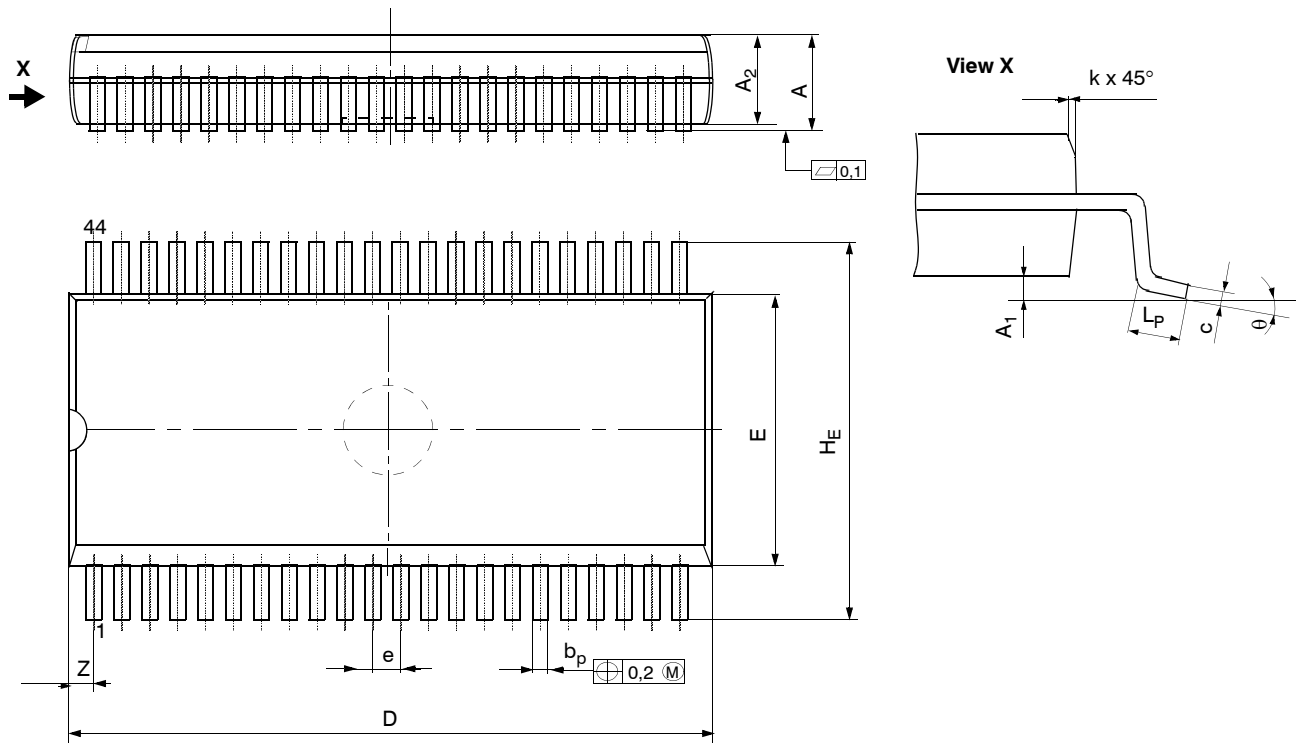


	Package SSOP44 (300 mil)	MDS 771
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Dimensions in millimetres

1 Dimensions

Dimensions of Sub-Group B1	
A _{max}	2,64
b _{Pmin}	0,28
b _{Pmax}	0,51
e _{nom}	0,8
H _{Emin}	10,11
H _{Emax}	10,51
L _{Pmin}	0,4
Z _{max}	0,51

Dimensions of Sub-Group C1	
A _{min}	2,44
A _{1min}	0,1
A _{1max}	0,3
A _{2min}	2,14
A _{2max}	2,54
c _{min}	0,23
c _{max}	0,32
D _{min} *	17,73
D _{max} *	17,93
E _{min} *	7,40
E _{max} *	7,60
k _{min}	0,5
θ _{min}	0°
θ _{max}	8°

- 2 Weight** ≤ 0,8 g
- 3 Package Body Material** Low Stress Epoxy
- 4 Lead Material** Cu-Alloy
- 5 Lead Finish** solder plating
- 6 Lead Form** Z-bends

* without mold-flash

Zentrum Mikroelektronik Dresden		
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Check: signed Marx	Quality: signed Tina Kochan	